

L Number	Hits	Search Text	DB	Time stamp
1	79111	356/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 15:04
2	5655	356/\$.ccls. and planar	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 15:05
3	5863	356/\$.ccls. and planar\$5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 15:05
4	994	(356/\$.ccls. and planar\$5) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 15:05
5	808	((356/\$.ccls. and planar\$5) and wafer) and reflected	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 15:05
6	282	((356/\$.ccls. and planar\$5) and wafer) and reflected) and analyzing	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 15:06
7	96	((356/\$.ccls. and planar\$5) and wafer) and reflected) and analyzing) and refractive adj3 index\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 15:06
8	49	((356/\$.ccls. and planar\$5) and wafer) and reflected) and analyzing) and refractive adj3 index\$2) and reduction	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 15:08
9	529	356/\$.ccls. and developer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 15:08
10	86	(356/\$.ccls. and developer) and material adj2 layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 15:09
11	28	((356/\$.ccls. and developer) and material adj2 layer) and processor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 15:14
12	3	356/\$.ccls. and volume adj2 developer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 15:15
13	0	356/\$.ccls. and concentration adj2 developer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/02 15:16